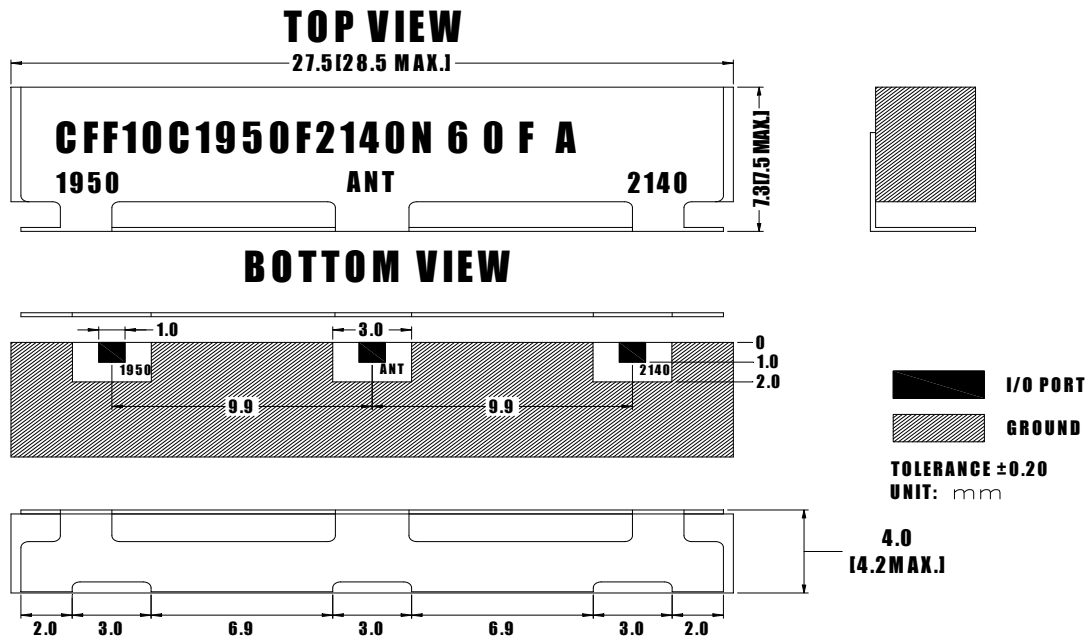


Electrical Specification

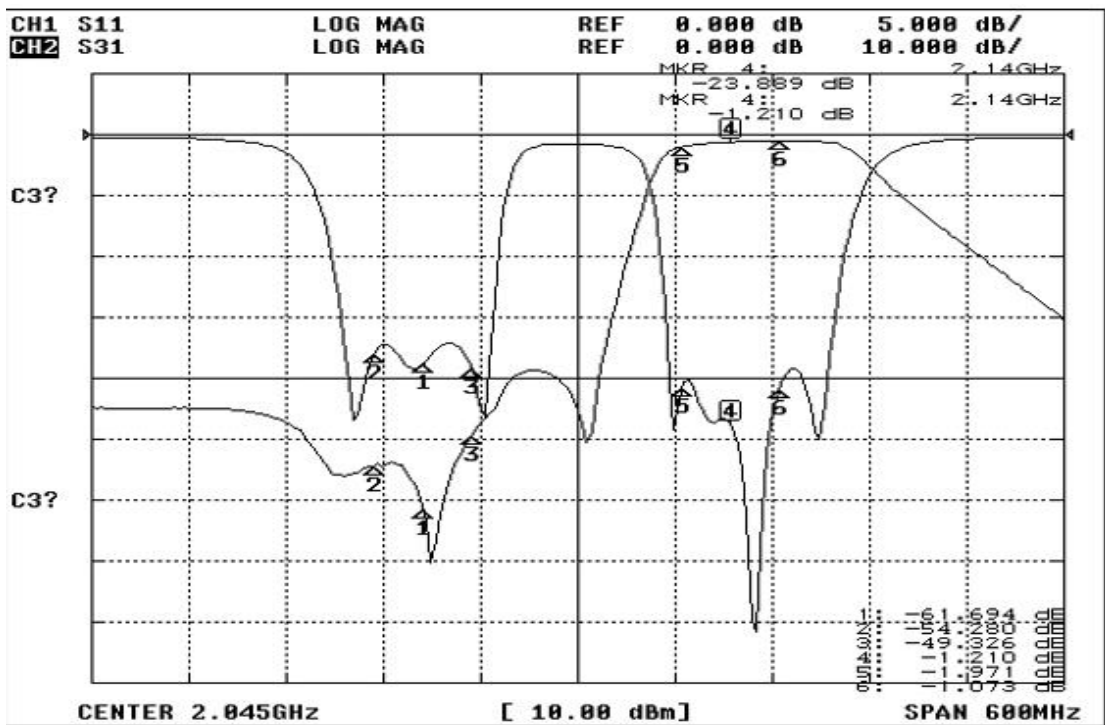
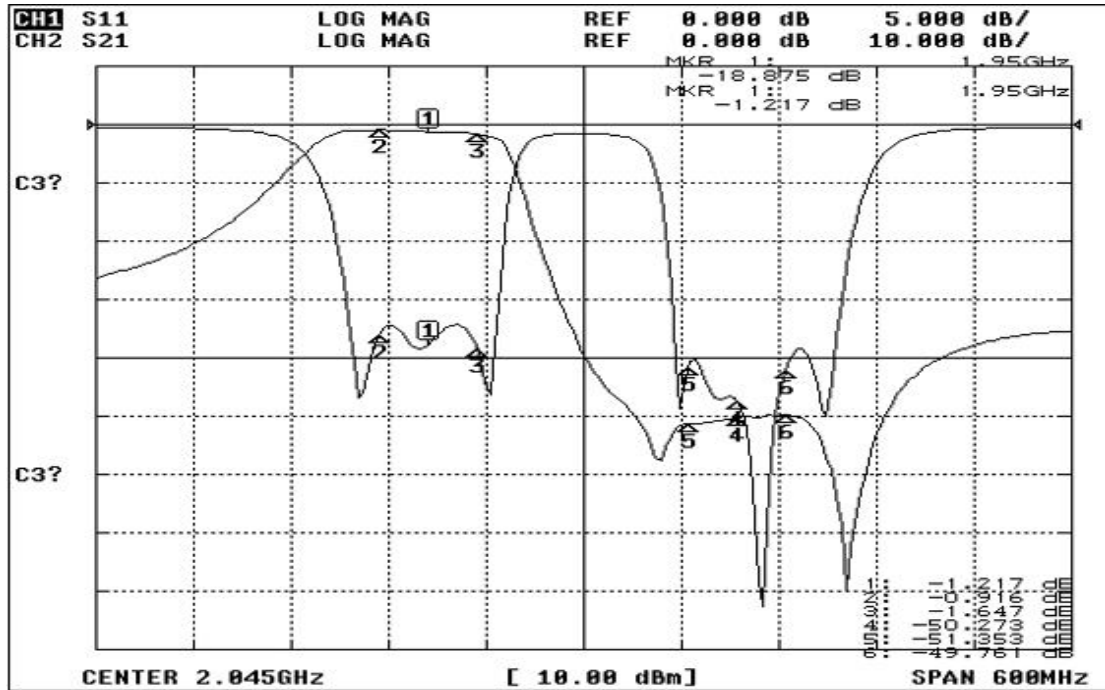
ITEMS	ANT>>LOW	ANT>>High	UNIT
Center Frequency [fo]	1950	2140	MHz
Bandwidth [BW]	fo ±30 [1920~1980]	fo ±30 [2110~2170]	MHz
Insertion Loss in BW	3.5	3.5	dB max
Ripple in BW	1.5	1.5	dB max
Return Loss in BW <input checked="" type="checkbox"/> ANT Port	18.0	18.0	dB min
VSW Rin BW <input checked="" type="checkbox"/> ALL Port			max
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	45dB min @ [2110~2170]	45dB min @ [1920~1980]	MHz
	dB min @ fo ± [~]	dB min @ fo ± [~]	MHz
	dB min @ fo ± [~]	dB min @ fo ± [~]	MHz
	dB min @ fo ± [~]	dB min @ fo ± [~]	MHz
Group Delay Variation	dB min@[~]		ns max
	dB min@[~]		
Input Power	3		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

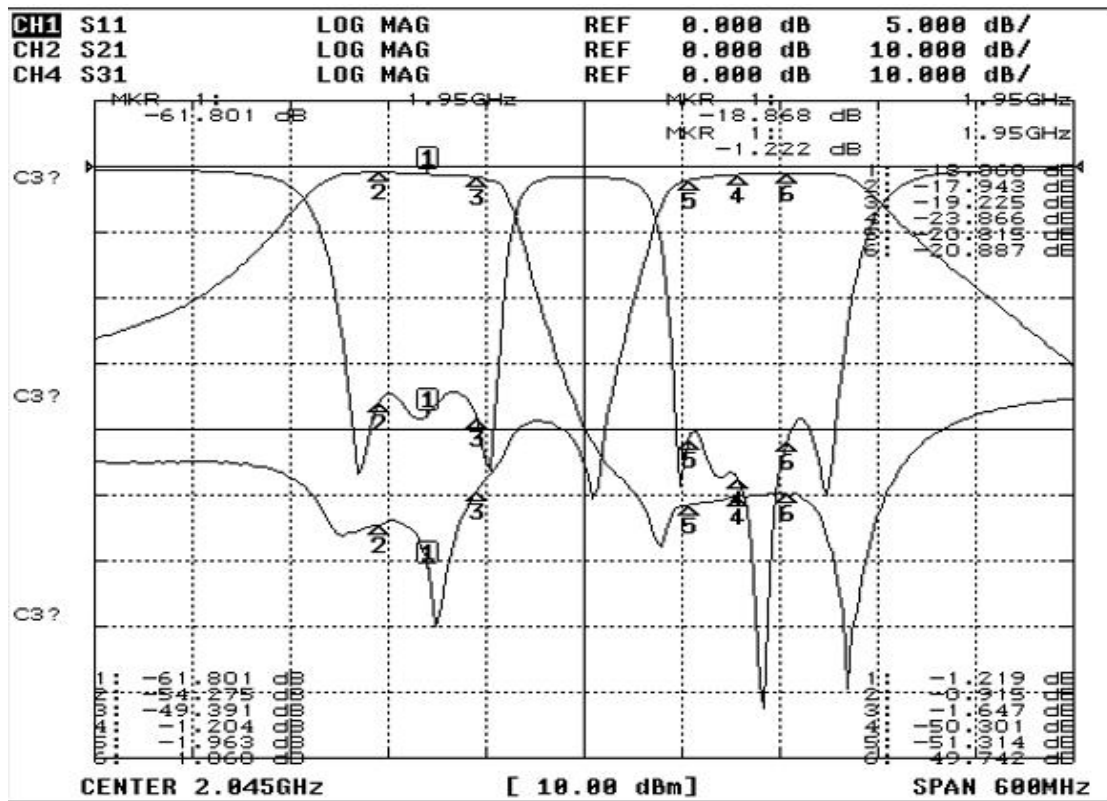
Mechanical Specification



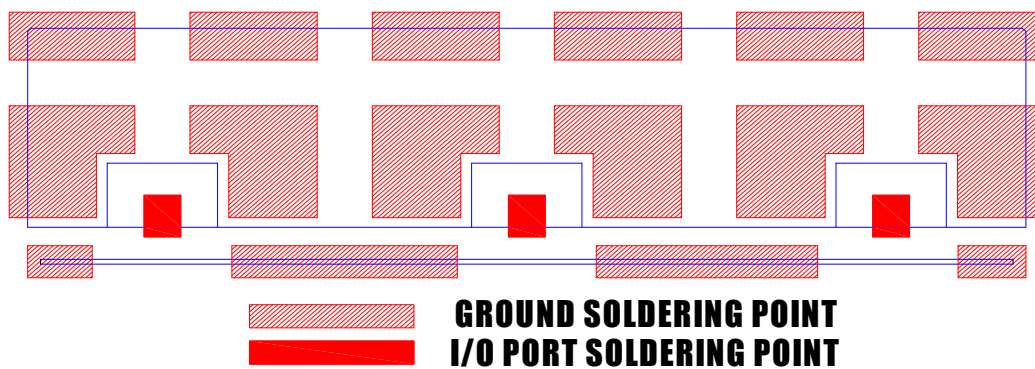


Plot Data

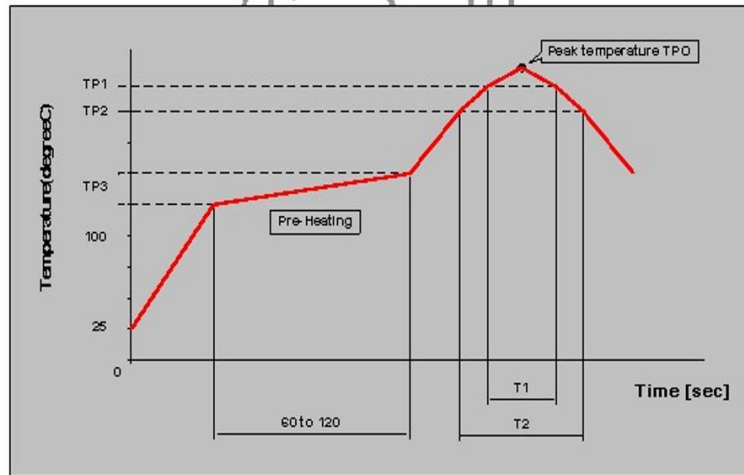




 Recommended PC Board Pattern



 **Soldering Condition**



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/-0	240	20	220	70	150 to 180